

ABSTRACT

WEDGE-BONDING OF WIRES IN ELECTRONIC DEVICE MANUFACTURE

5 In the manufacture of electronic devices (22, 22'), e.g. discrete semiconductor power devices or ICs, a reversible bonding tool (10) is used having a bonding tip or wedge (1, 2) at each of its opposite ends (11, 12). After extensive use of the wedge-tip (1) at one end (11) for bonding wires (21), the tip (1) is worn somewhat. Instead of needing to replace the bond tool as in the prior art, the tool (10) in accordance with the invention is then reversed to use the
10 wedge-tip (2) at the opposite end (12) for bonding further wires (20'). Thus, a cost saving is achieved with regard to tool material.

15 [Figures 2A & 2B]